

2SD1272

Silicon NPN epitaxial planar type

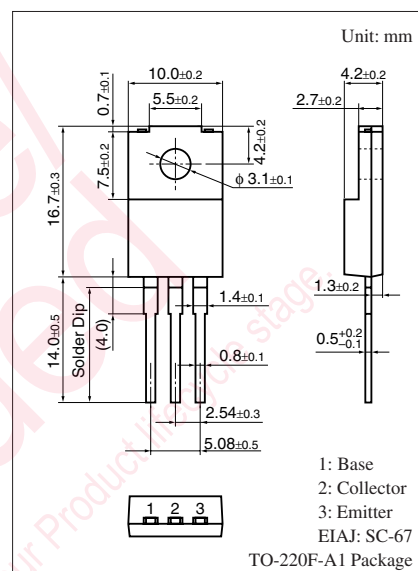
For high-speed switching and high current amplification ratio

■ Features

- High forward current transfer ratio h_{FE}
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	200	V
Collector-emitter voltage (Base open)	V_{CEO}	150	V
Emitter-base voltage (Collector open)	V_{EBO}	6	V
Collector current	I_C	2.5	A
Peak collector current	I_{CP}	1	A
Collector power dissipation $T_C = 25^\circ\text{C}$	P_C	40	W
		2.0	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



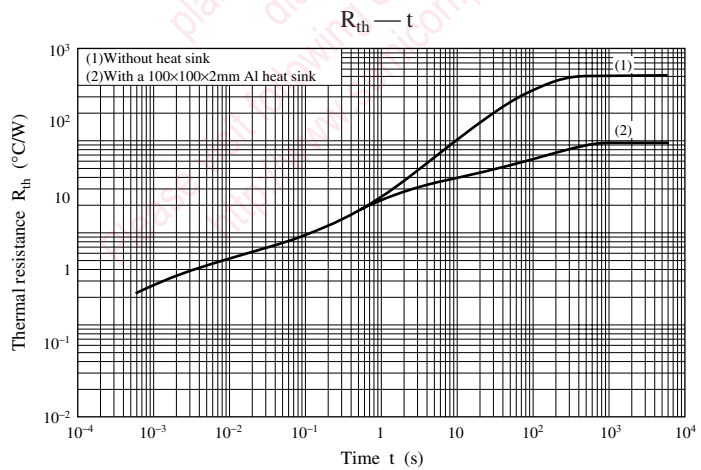
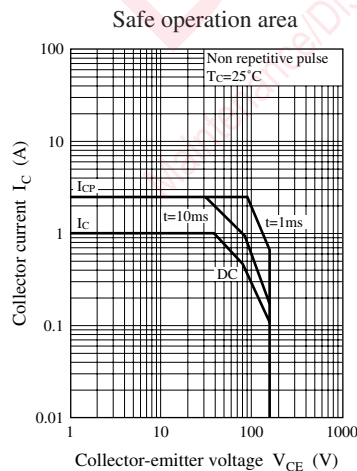
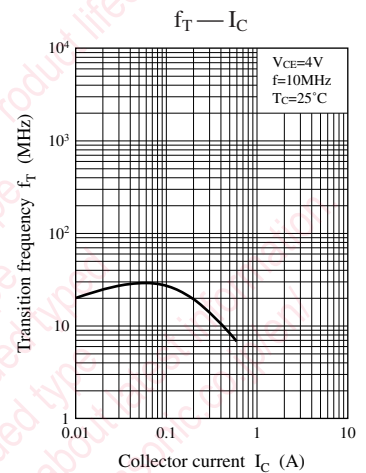
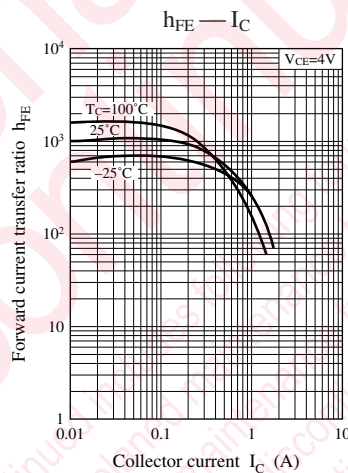
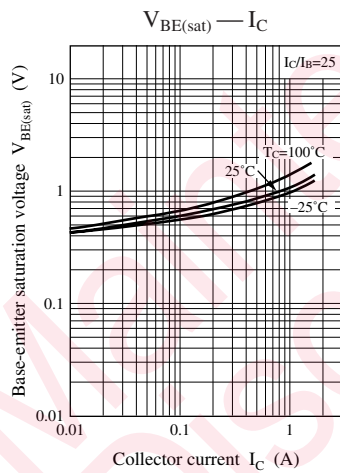
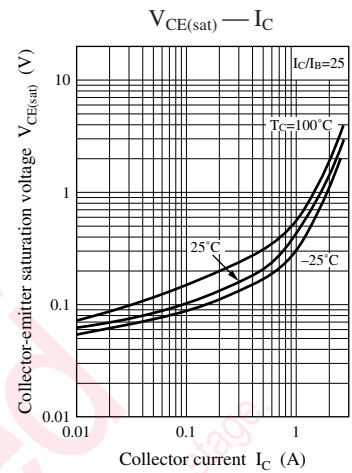
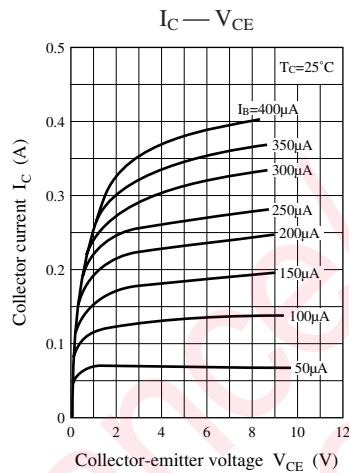
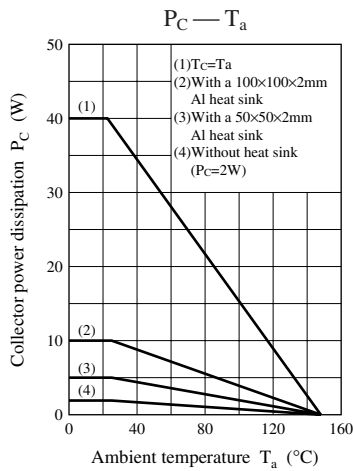
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 25\text{ mA}, I_B = 0$	150			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 200\text{ V}, I_E = 0$			100	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 6\text{ V}, I_C = 0$			100	μA
Forward current transfer ratio *	h_{FE}	$V_{CE} = 4\text{ V}, I_C = 0.2\text{ A}$	500		2000	—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 0.5\text{ A}, I_B = 0.02\text{ A}$			1	V
Transition frequency	f_T	$V_{CE} = 4\text{ V}, I_C = 0.1\text{ A}, f = 10\text{ MHz}$		25		MHz

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	P
h_{FE}	500 to 1 200	800 to 2 000



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